Rogers to Highlight Pair of High-Flying Laminates for Satellite Communications at Satellite 2012

Rogers Corporation will be highlighting two of its leading printed-circuit-board (PCB) laminate materials for commercial and military satellite-communications (satcom) electronic applications at the upcoming Satellite 2012 Exhibition.

The Satellite 2012 Exhibition (www.satellite2012.com), being held March 12-14 in the Walter E. Washington Convention Center (Washington, DC), is expected to draw more than 350 exhibiting companies involved in satcom markets at all levels of the design and manufacturing supply chain. Representatives from Rogers Advanced Circuit Materials Division will be on hand at Booth #1533 to offer advice and guidance on the use of their reliable PCB materials, in particular, their low-loss RT/duroid® 5880LZ laminates and their high thermal conductivity RT/duroid 6035HTC circuit materials.

RT/duroid 6035HTC is a ceramic-filled, PTFE composite material designed especially for high-frequency, high-power applications, such as antenna beam-forming networks and power amplifiers for wireless cellular communications networks. With a relative dielectric constant of 3.50 at 10 GHz, low loss by merit of its dissipation factor of 0.0013 at 10 GHz, the high-thermal-conductivity (HTC) fluoropolymer composite contains a unique filler system, enabling a thermal conductivity of 1.44 W/m/K, while maintaining low drill wear versus other competitive offerings.

In addition, when high electrical performance versus weight is critical, Rogers RT/duroid 5880LZ laminate materials feature the industry’s lowest available dielectric constant of 1.96 in the z-axis at 10 GHz with a TCDk of +22ppm/ºC. RT/duroid 5880LZ is also light weight, having a specific gravity of 1.3 – 1.4, making it suitable for airborne satellite applications. These materials offer low loss, evidenced by a dissipation factor of typically 0.0019 at 10 GHz. Usable at satellite frequencies to Ku-band and beyond, these RoHS-compliant circuit materials feature a low z-axis coefficient of thermal expansion (CTE) of 41.5 ppm/ºC for reliable plated through holes (PTHs) in multilayer circuits.

For more information, visit www.rogerscorp.com [1].

Posted by Janine E. Mooney, Editor

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[1] http://www.rogerscorp.com